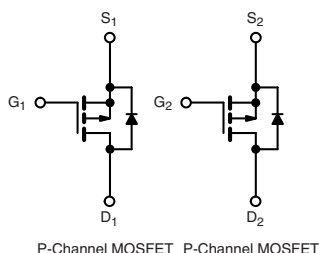
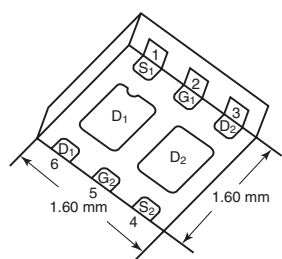


Dual P-Channel 20 V (D-S) MOSFET

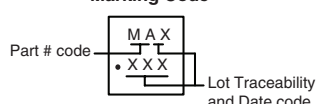
PRODUCT SUMMARY

V_{DS} (V)	- 20
$R_{DS(on)}$ (Ω) at $V_{GS} = -4.5$ V	0.295
$R_{DS(on)}$ (Ω) at $V_{GS} = -2.5$ V	0.420
$R_{DS(on)}$ (Ω) at $V_{GS} = -1.8$ V	0.560
I_D (A) ^f	- 2.6
Configuration	Dual

PowerPAK SC75-6L-Dual



Marking Code



FEATURES

- High Quality Manufacturing Process Using SMM Process Flow
- **Halogen-free According to IEC 61249-2-21 Definition**
- TrenchFET® Power MOSFET
- New Thermally Enhanced PowerPAK® SC-75 Package
 - Small Footprint Area
- Compliant to RoHS Directive 2002/95/EC
- Find out more about Vishay's Medical Products at: www.vishay.com/medical-mosfets



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATION EXAMPLES

- Medical Implantable Applications Including
 - Drug Delivery Systems
 - Defibrillators
 - Pacemakers
 - Hearing Aids
 - Other Implantable Devices
- Load Switch, PA Switch and Battery Switch for Portable Devices

ORDERING INFORMATION

Package	PowerPAK SC-75
Lead (Pb)-free and Halogen-free	SMMB911DK-T1-GE3

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	- 20	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current ($T_J = 150$ °C)	I_D	$T_C = 25$ °C	A
		$T_C = 70$ °C	
		$T_A = 25$ °C ^{a, b}	
		$T_A = 70$ °C ^{a, b}	
Pulsed Drain Current	I_{DM}	- 5	A
Continuous Source-Drain Diode Current	I_S	$T_C = 25$ °C	
		$T_A = 25$ °C ^{a, b}	
Maximum Power Dissipation	P_D	$T_C = 25$ °C	W
		$T_C = 70$ °C	
		$T_A = 25$ °C ^{a, b}	
		$T_A = 70$ °C ^{a, b}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature) ^{c, d}		260	°C

SMMB911DK

Vishay Siliconix



THERMAL RESISTANCE RATINGS

PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Ambient ^{a, e}	$t \leq 5$ s	R_{thJA}	90	115	°C/W
Junction-to-Case (Drain)	Steady State	R_{thJC}	32	40	

Notes

- a. Surface mounted on 1" x 1" FR4 board.
b. $t = 5$ s.
c. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SC-75 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
e. Maximum under steady state conditions is 125 °C/W.
f. Based on $T_C = 25$ °C.

SPECIFICATIONS $T_J = 25$ °C, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA		- 20	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		-	- 19	-	mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			-	1.9	-	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 0.4	-	- 1	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = - 20 V	-	-	- 1	μA
		V _{GS} = 0 V	V _{DS} = - 20 V, T _J = 55 °C	-	-	- 10	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 4.5 V	V _{DS} ≤ 5 V	5	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V	I _D = - 1.5 A	-	0.242	0.295	Ω
		V _{GS} = - 2.5 V	I _D = - 1.2 A	-	0.345	0.420	
		V _{GS} = - 1.8 V	I _D = - 0.18 A	-	0.455	0.560	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 10 V, I _D = - 1.5 A		-	3	-	S
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = - 10 V, f = 1 MHz	-	115	-	pF
Output Capacitance	C _{oss}			-	30	-	
Reverse Transfer Capacitance	C _{rss}			-	20	-	
Total Gate Charge	Q _g	V _{GS} = - 8 V	V _{DS} = - 10 V, I _D = - 1.7 A	-	2.6	4.0	nC
		V _{GS} = - 4.5 V	V _{DS} = - 10 V, I _D = - 1.7 A	-	1.6	2.5	
Gate-Source Charge	Q _{gs}			-	0.3	-	
Gate-Drain Charge	Q _{gd}			-	0.5	-	
Gate Resistance	R _g	f = 1 MHz		-	7	-	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 7.1 Ω I _D ≡ - 1.4 A, V _{GEN} = - 4.5 V, R _g = 1 Ω		-	12	20	ns
Rise Time	t _r			-	45	70	
Turn-Off Delay Time	t _{d(off)}			-	10	15	
Fall Time	t _f			-	31	50	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 7.1 Ω I _D ≡ - 1.4 A, V _{GEN} = - 8 V, R _g = 1 Ω		-	3	10	
Rise Time	t _r			-	25	40	
Turn-Off Delay Time	t _{d(off)}			-	10	15	
Fall Time	t _f			-	10	15	
Source-Drain Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C		-	-	- 2.6	A
Pulse Diode Forward Current	I _{SM}			-	-	5	

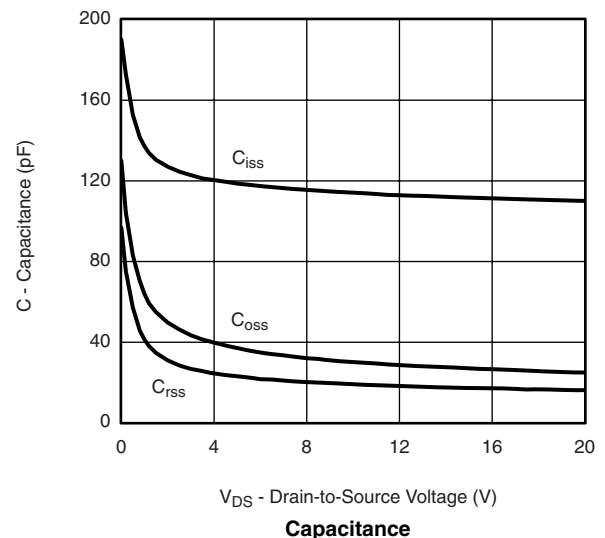
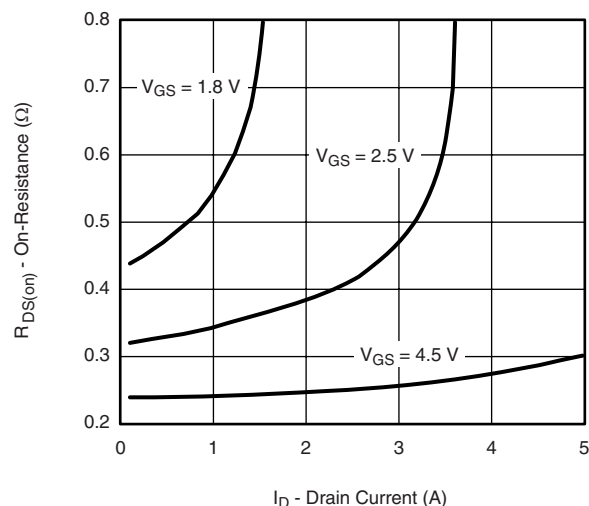
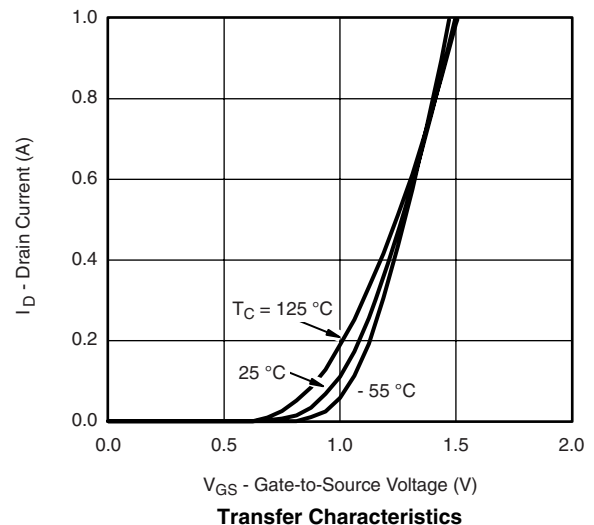
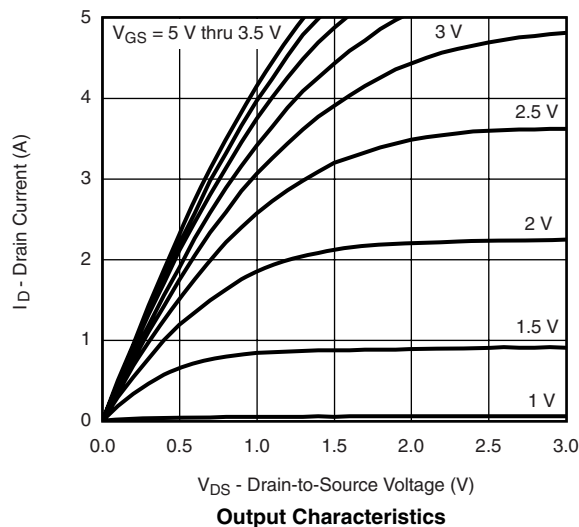
**SPECIFICATIONS** $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted

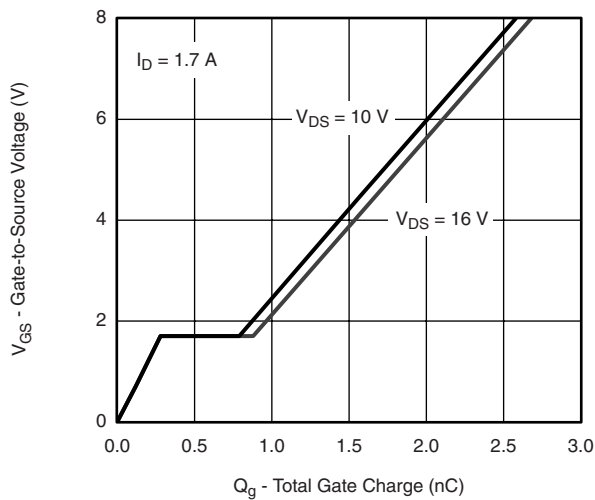
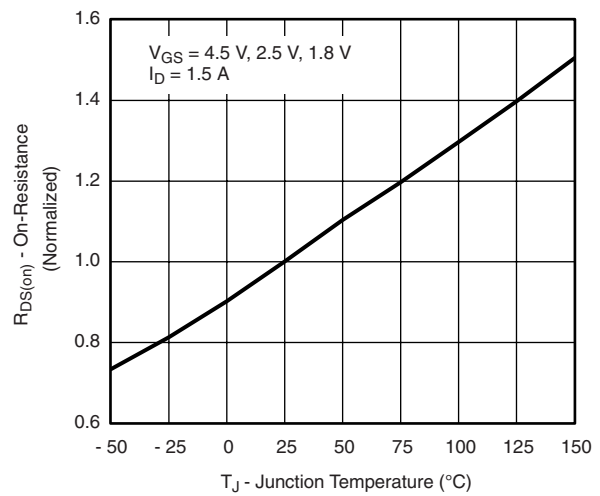
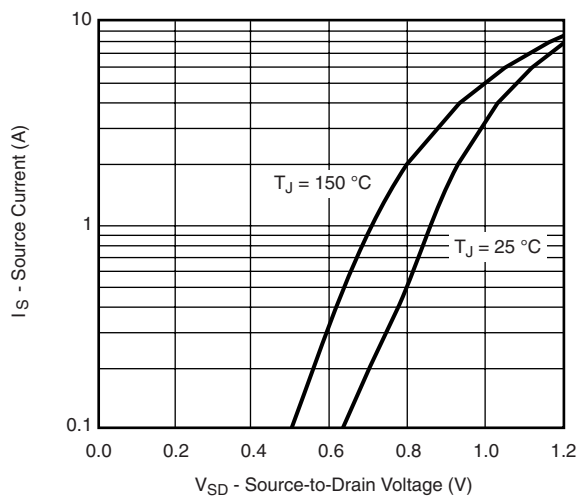
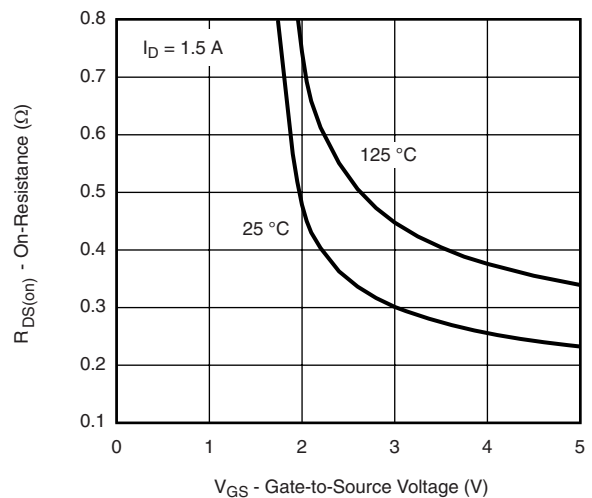
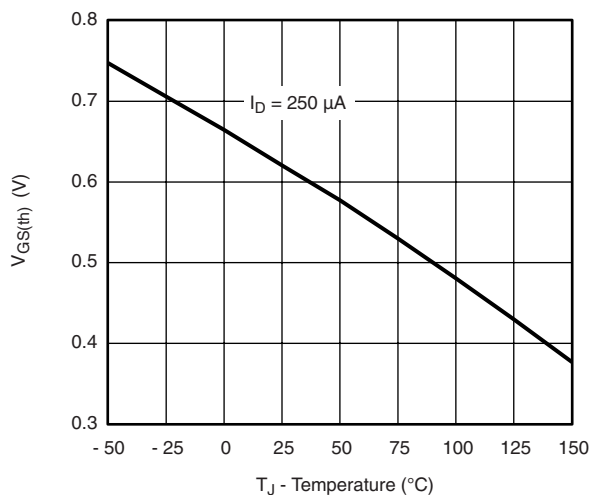
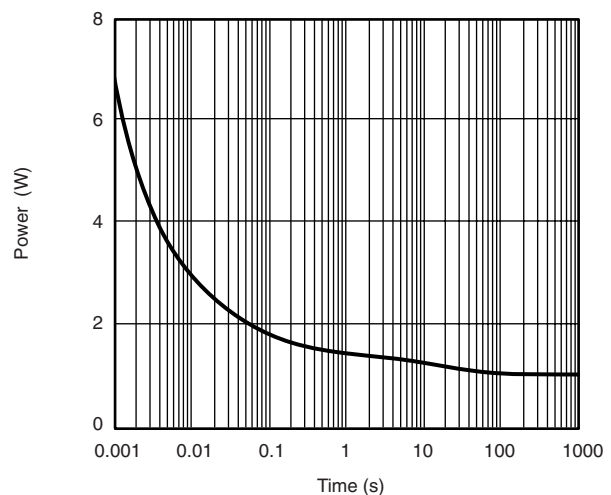
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Source-Drain Body Diode Characteristics						
Body Diode Voltage	V_{SD}	$I_S = -1.4\text{ A}$, $V_{GS} = 0\text{ V}$	-	-0.8	-1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -1.4\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$	-	25	50	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	26	50	nC
Reverse Recovery Fall Time	t_a		-	19	-	ns
Reverse Recovery Rise Time	t_b		-	6	-	

Notes

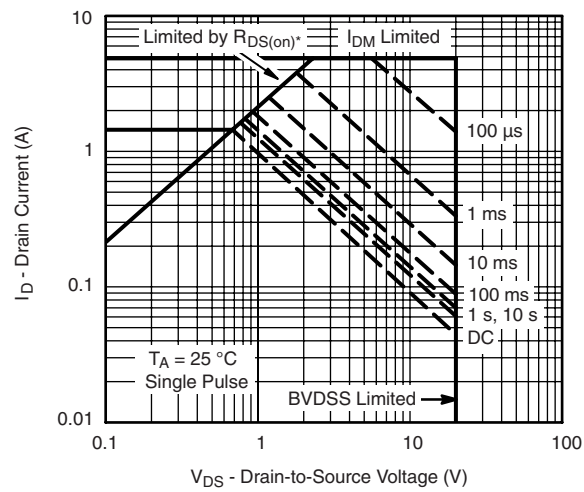
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS $T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted

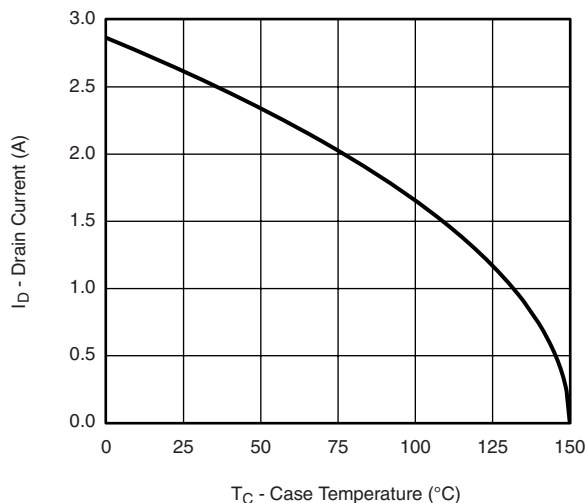
TYPICAL CHARACTERISTICS $T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted**Gate Charge****On-Resistance vs. Junction Temperature****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power, Junction-to-Ambient**

TYPICAL CHARACTERISTICS $T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

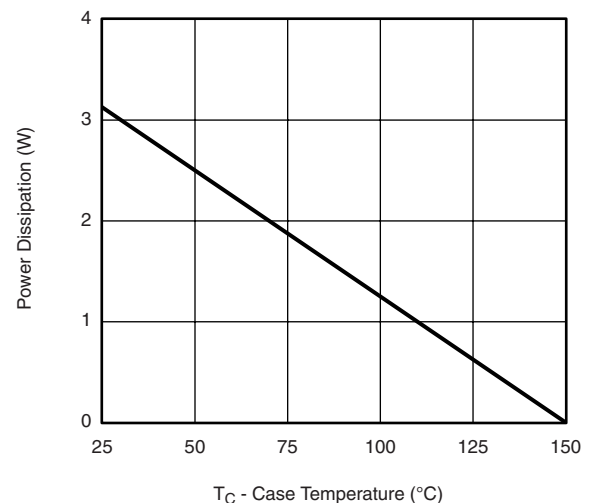


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

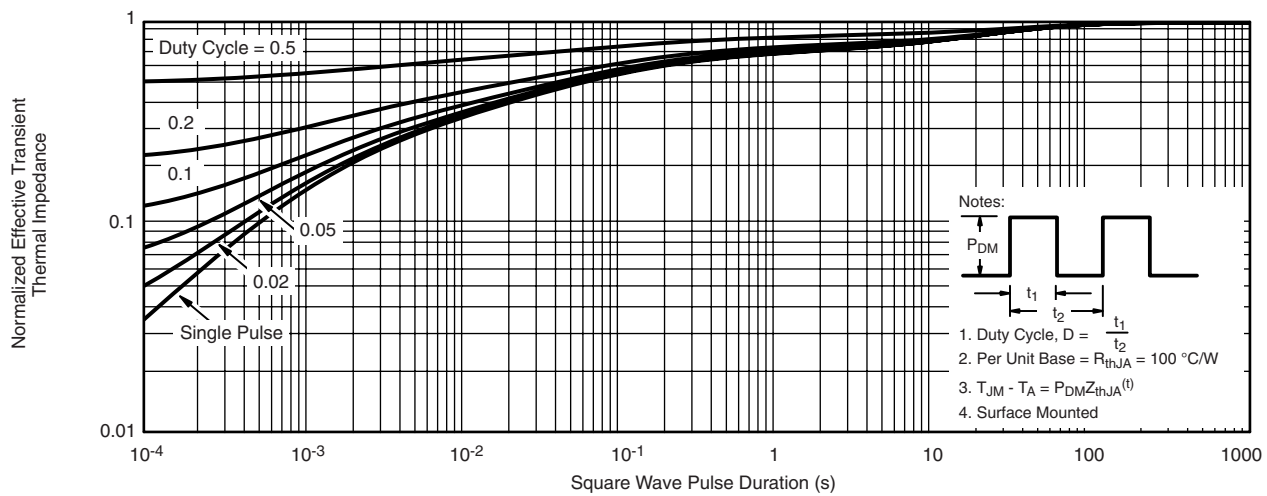
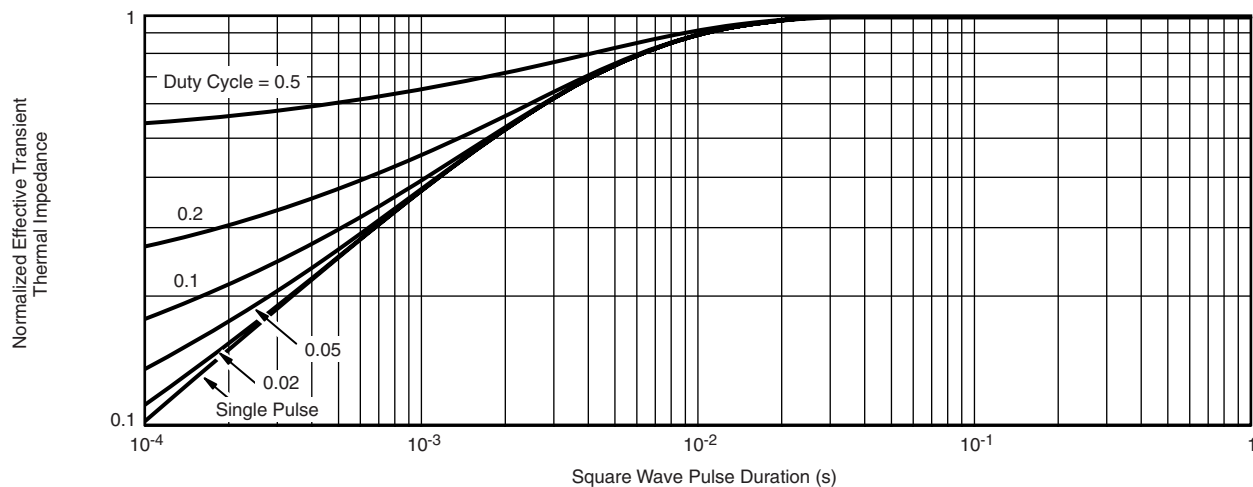


Current Derating*



Power Derating

* The power dissipation P_D is based on $T_{J(max)} = 150\text{ }^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS $T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Case**

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